

Part Number: AP1608P1C

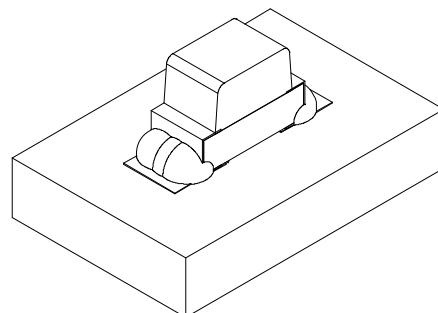
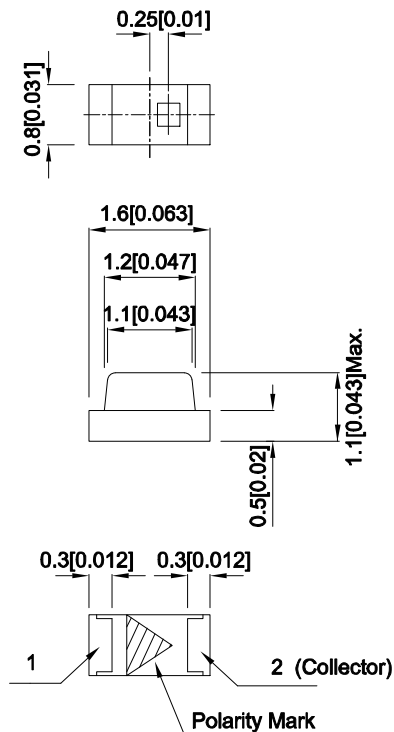
Features

- 1.6mmX0.8mm SMD LED, 1.1mm thickness.
- Mechanically and spectrally matched to the infrared emitting LED lamp.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

Made with silicon phototransistor chips.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.1 (0.004") unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.



Electrical / Optical Characteristics at TA=25°C

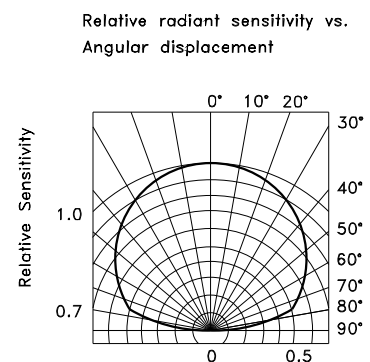
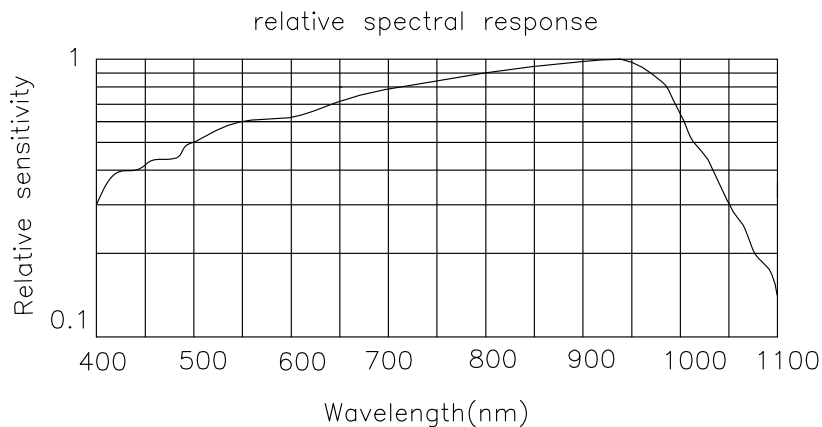
Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
V _{BR CEO}	Collector-to-Emitter Breakdown Voltage	30			V	I _C =100uA E _e =0mW/cm ²
V _{BR ECO}	Emitter-to-Collector Breakdown Voltage	5			V	I _E =100uA E _e =0mW/cm ²
V _{CE (SAT)}	Collector-to-Emitter Saturation Voltage			0.8	V	I _C =2mA E _e =20mW/cm ²
I _{CEO}	Collector Dark Current			100	nA	V _{CE} =10V E _e =0mW/cm ²
T _R	Rise Time (10% to 90%)		15		us	V _{CE} = 5V I _C =1mA R _L =1000Ω
T _F	Fall Time (90% to 10%)		15		us	
I _(ON)	On State Collector Current	0.1	0.3		mA	V _{CE} = 5V E _e =1mW/cm ² λ=940nm
λ0.1	Range of spectral bandwidth	420		1120	nm	
λ _p	Wavelength of peak sensitivity		940		nm	
2θ1/2	Angle of half sensitivity		150		deg	

Absolute Maximum Ratings at TA=25°C

Parameter	Max.Ratings
Collector-to-Emitter Voltage	30V
Emitter-to-Collector Voltage	5V
Power Dissipation at (or below) 25°C Free Air Temperature	100mW
Operating Temperature	-40°C To +85°C
Storage Temperature	-40°C To +85°C

Note:

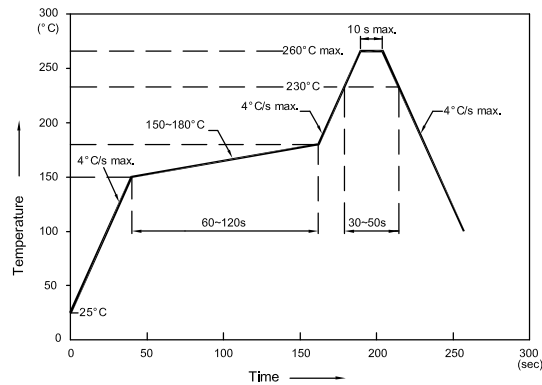
1. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



AP1608P1C

Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

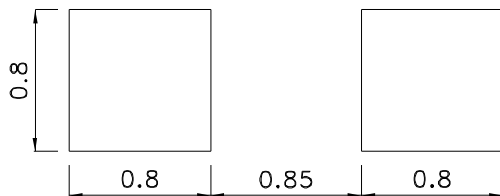
Reflow Soldering Profile For Lead-free SMT Process.



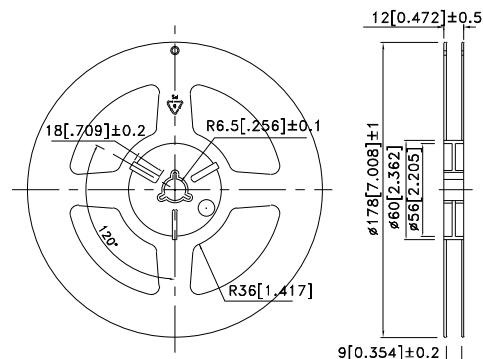
NOTES:

1. We recommend the reflow temperature 245°C (+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

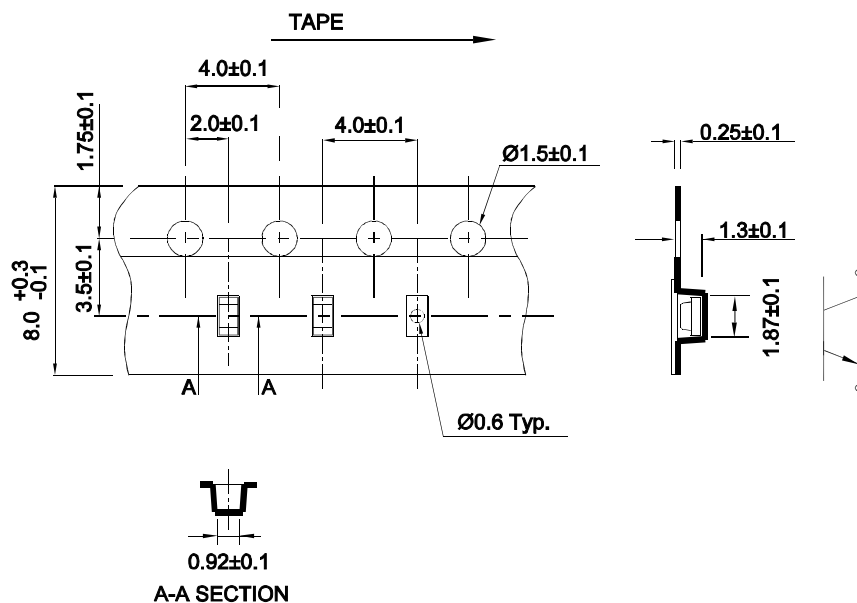
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension

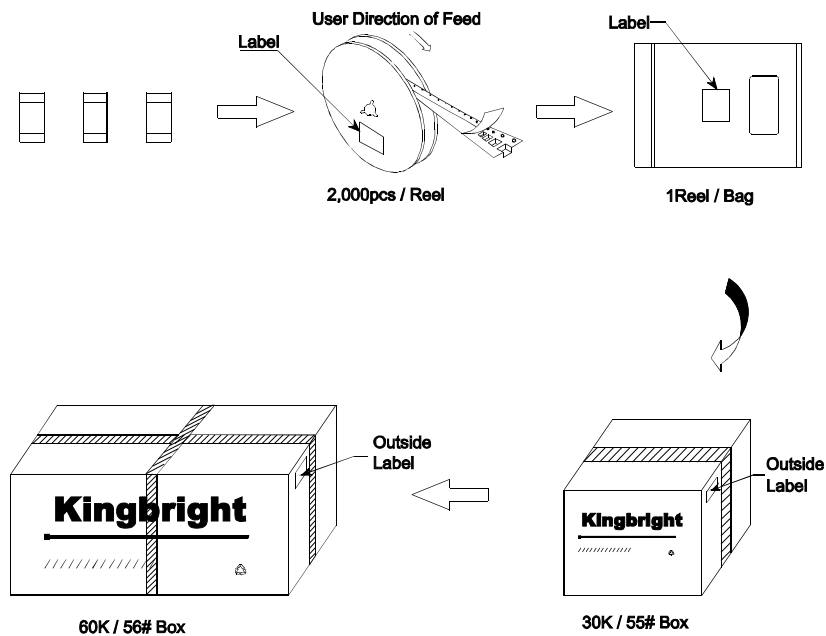


Tape Specifications (Units : mm)



PACKING & LABEL SPECIFICATIONS

AP1608P1C



Kingbright	
P/NO: AP1608XXX	
QTY: 2,000 pcs	Q.C.
S/N: XXXX	QC XXXXXXX PASSED
CODE: XXX	
LOT NO:	
	
RoHS Compliant	

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